

Appl. No. 10/024,936

IN THE CLAIMS

1. (Currently Amended) A ball grid array (BGA) package assembly having a plurality of external connection contacts, comprising:

a first device, disposed on the BGA package, and having a plurality of electrical connections connected to a first set of the external electrical connection contacts; and

a second device, disposed on the BGA package, and having a plurality of electrical connections connected to a second set of the external electrical connection contacts;

wherein the first and second sets of the external electrical connections are segregated in two sections which are electrically isolated from each other, and the two sections are separated by at least a first distance wherein the first distance is based upon an expected difference in operating voltage between the first device and the second device.

2. (Previously Presented) The package of claim 1, wherein the first distance is in accordance with a predetermined standard.

3. (Previously Presented) The package of claim 2, wherein the standard specifies a physical separation distance between conductors based at least upon a voltage between the conductors.

4. (Original) The package of claim 1, further comprising:

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a plurality of layers, including a signal layer, a power layer, a ground layer and a bottom layer;

wherein each of the layers includes two sets of electrical connections that are segregated in two sections which are electrically isolated from each other, and the two sets of electrical connections are respectively connected to the first and second devices.

5. (Previously Presented) The package of claim 4, wherein the standard specifies a physical separation distance between conductors based at least upon a voltage between the conductors.

6. (Original) The package of claim 1, wherein the first and second devices are semiconductor integrated circuit (IC) devices.

7. (Original) The package of claim 6, wherein the IC devices are communications devices.

13. (Previously Presented) A ball grid array package, comprising:

a plurality of layers, including a signal layer, a power layer, a ground layer and a bottom layer;

wherein each of the layers includes a plurality of sets of electrical conductors that are segregated into a corresponding plurality of sections which are electrically isolated from one another by a minimum distance based upon an

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expected voltage difference between the sets of electrical conductors, each of the plurality of sets of electrical conductors being adapted for connection to a corresponding integrated circuit.

14. (Original) The package of claim 13, wherein the plurality of sections are segregated in accordance with a predetermined standard.

15. (Previously Presented) The package of claim 14, wherein the predetermined standard specifies a physical separation distance between conductors of the package based at least upon a voltage between the conductors.

16. (Original) The package of claim 13, wherein the first and second devices are semiconductor integrated circuit (IC) devices.

17. (Original) The package of claim 16, wherein the IC devices are communications devices.